



Side contact for perpendicular grounding

Feature

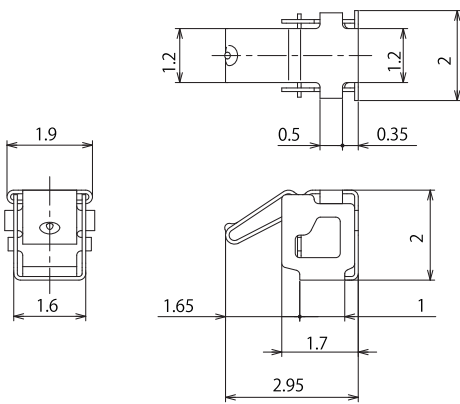
- Ideal for applications where standard grounding between parallel boards/ chassis is not possible .
- Due to low profile design (2mm), it's suitable for small electronic devices
- Operating temperature: -40~125°C

Material

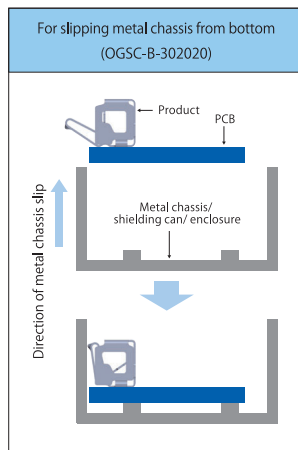
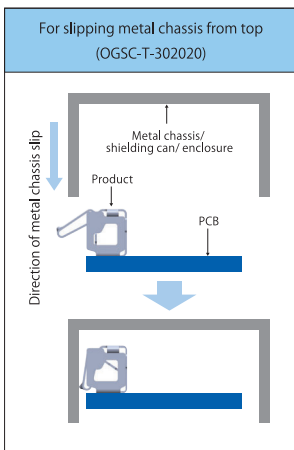
- Corson alloy (t0.08mm)

Specification

● Dimensions



Item	OGSC-T-302020	OGSC-B-302020
Applications	Ground contact for SMD	
Material	Corson alloy(t0.08mm)	
Surface treatment	Sn reflow plating (Underlying Cu plating)	
Recommended operating temperature range(°C)	-40 ~ 125	
Compression range(mm)	0.3 ~ 1.0	
Initial resistance (Ω)	≤0.05	
Initial compression force(N)	0.2 ~ 3.1	0.4 ~ 3.0



Heat cycle test

